

Objective lenses

Parfocal distance 60mm

Objective lens	W.D. (mm)	NA
5×	23.50	0.15
10×	17.50	0.30
20×	4.50	0.45
50× Apo	2.00	0.80
100× Apo	2.00	0.90
150× Apo	1.50	0.90

Objective lens (long working distance)	W.D. (mm)	NA
20× ELWD	19.00	0.40
50× ELWD	11.00	0.60
100× ELWD	4.50	0.80

Objective lens (super long working distance)	W.D. (mm)	NA
10× SLWD	37.00	0.20
20× SLWD	30.00	0.30
50× SLWD	22.00	0.40
100× SLWD	10.00	0.60

Objective lens (glass thickness correction)	W.D. (mm)	NA
20× LCD	10.00	0.45
50× LCD	3.00	0.70
100× LCD	0.85/0.95	0.85

Parfocal distance 45mm

Objective lens (high NA)	W.D. (mm)	NA
50× Apo	0.35	0.95
100× Apo	0.32	0.95

Special objective lens (high NA)	W.D. (mm)	NA
5× LT	10.50	0.25
10× LT	1.60	0.50
20× LT	0.70	0.75

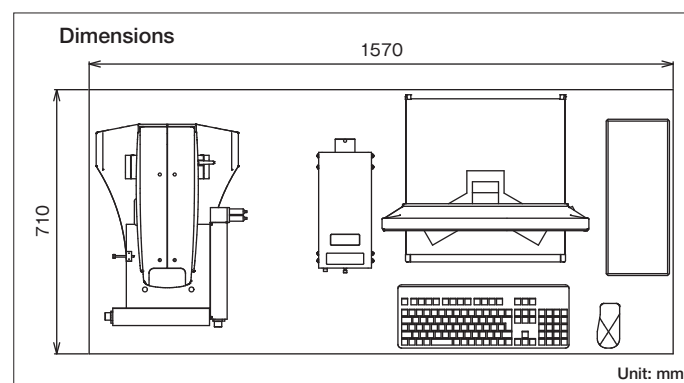
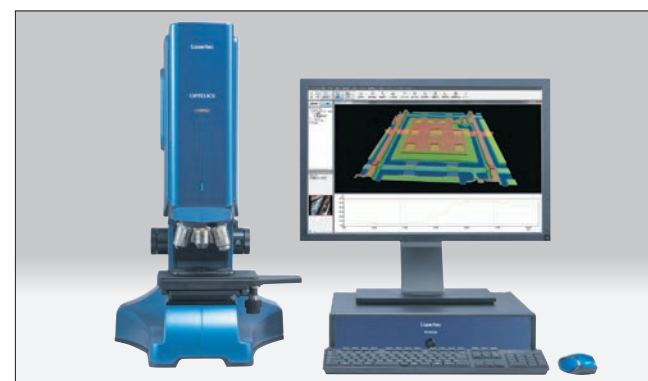
CFI60 series



Special objective lens (high NA)



Dimensions, Exterior



Lasertec HQ was certified ISO9001:2008 in June 2009.

- ⚠ Safety precautions: Read manuals before use. Use properly.
- This catalog provides information as of January 2015.
- The descriptions in this catalog are based on our research as of the product release.
- Product specifications are subject to change without notice. Neither manufacturer nor seller assumes any responsibility for damage caused by specification change.
- Screen images are simulated.



Laser radiation

Do not look into a laser beam.

405nm continuous wave with 100μW maximum

Class 2 laser product
JIS C 6802 : 2011

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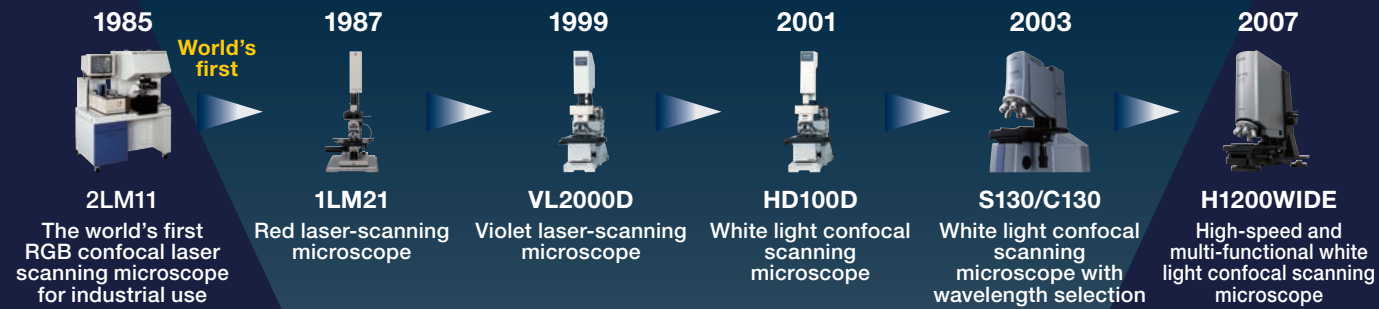
HYBRID LASER MICROSCOPE

OPTELICs
HYBRID

Optical technology at its best! Performance surpassing laser-scanning microscopes

In 1985, Lasertec released the world's first industrial-quality RGB confocal laser-scanning microscope

Lasertec then released red laser and violet laser microscopes and, in 2001, white light confocal scanning microscopes

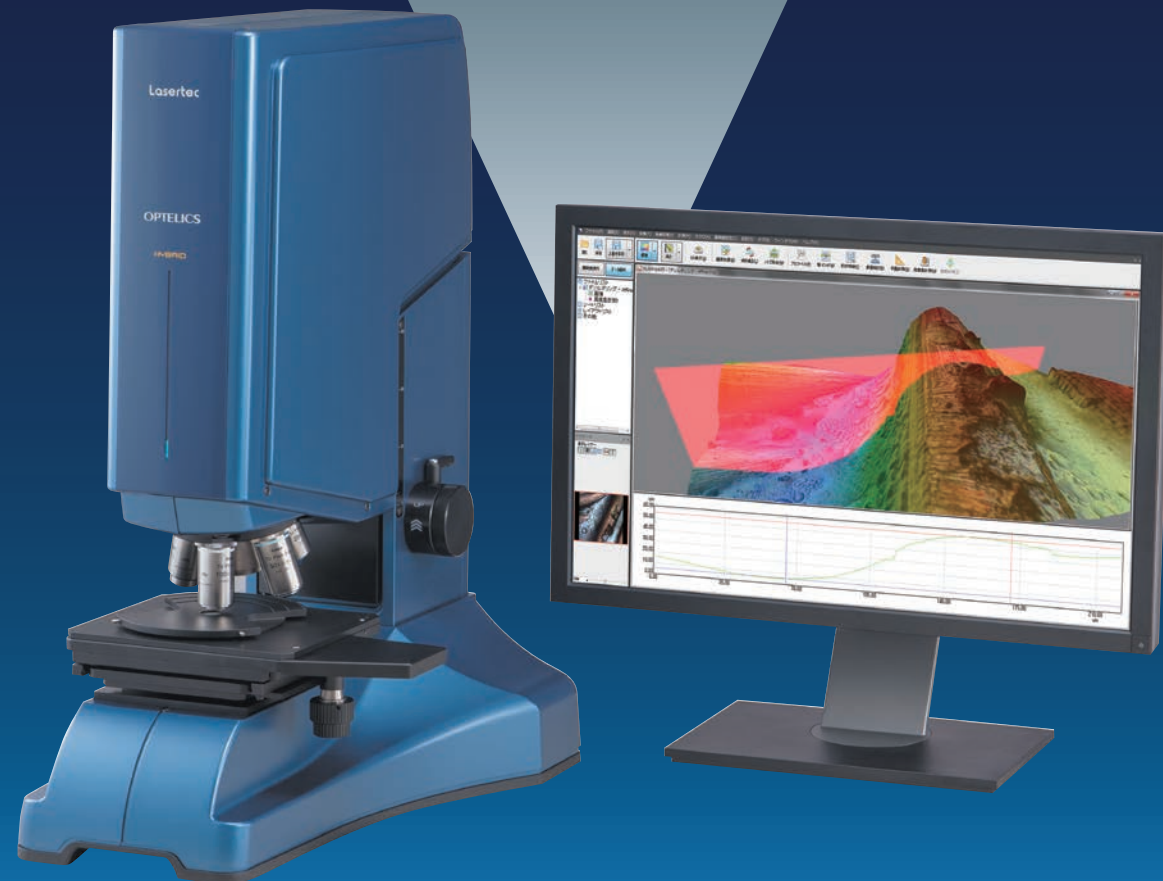


Today

With laser and white light source combined in one body

Multi-functional high-performance confocal microscope

OPTELICS HYBRID



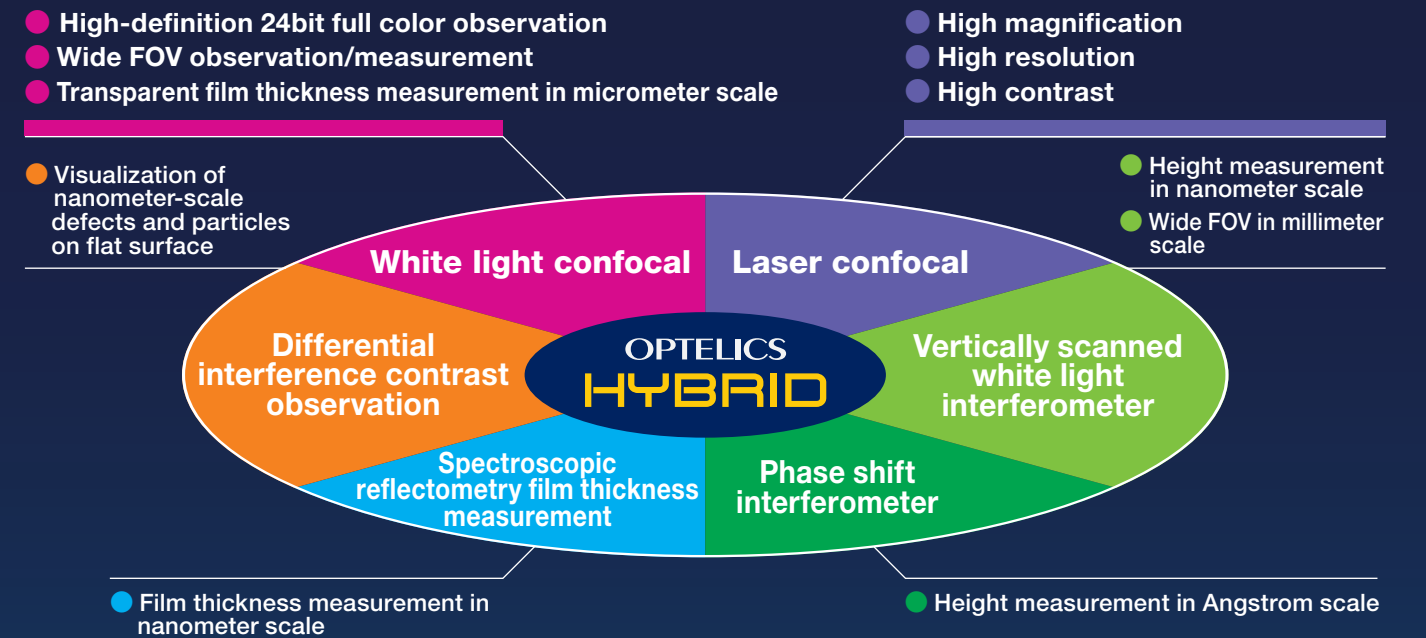
Multi-functional and high-performance HYBRID

White light confocal + Laser Confocal

White light confocal and laser confocal

6 functions in one body

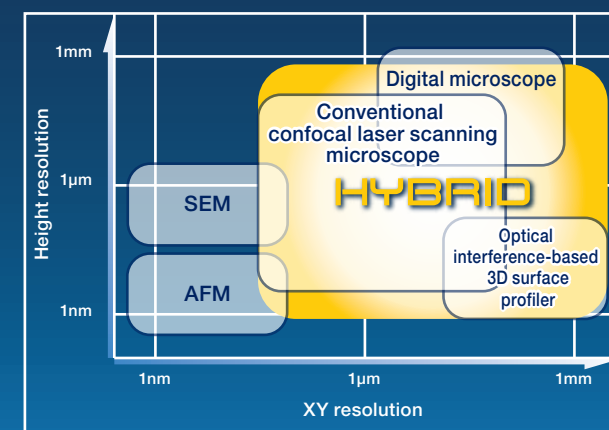
Featuring two sets of confocal optics combined with additional functions including interferometer, differential interference contrast observation, and spectroscopic reflectometry film thickness measurement, HYBRID performs multiple tasks that normally require several different tools.



Faster, wider and more accurate

Wide coverage and highly accurate measurement

One-stop solution

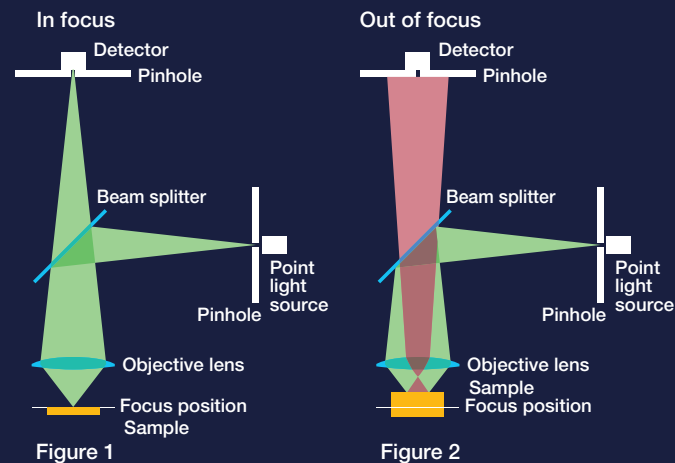


Tool	Interferometer surface profiler	Typical CLSM	SEM	Contact-type roughness gauge	AFM	HYBRID
Criteria						
Resolution (XY)	☹️	☺️	☺️	☹️	☺️	☺️
Color image	☹️	☹️	☹️	—	☹️	☺️
Wide FOV	☺️	☹️	☹️	☺️	☹️	☺️
3D measurement	☺️	☺️	☹️	☹️	☺️	☺️
Nano-scale profile measurement	☺️	☹️	☹️	☺️	☺️	☺️
Sample preparation	☺️	☺️	☹️	☺️	☺️	☺️
Speed	☺️	☹️	☹️	☹️	☹️	☺️

Confocal optics - basic principle of technology

Basic principle

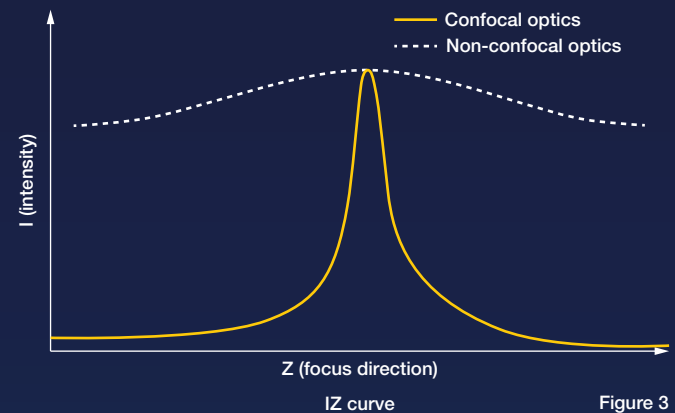
Confocal optics detects only the rays of light focused on the sample surface. Light emitted from the source and reflected by the sample surface reaches the detector only if it is focused at the pinhole in front of it (Figure1). This takes place only for the rays of light focused at the sample surface. The light rays from the sample surface in focal plane reach the detector but all others do not (Figure2). Confocal optics detects in-focus information only.



Merits of confocal optics

1. High resolution
2. High-contrast high-definition images without scattered light interference (Figure3)
3. Optical sectioning effect (see below)

These merits enable HYBRID to provide highly accurate measurement in x, y and z directions.



Optical sectioning effect

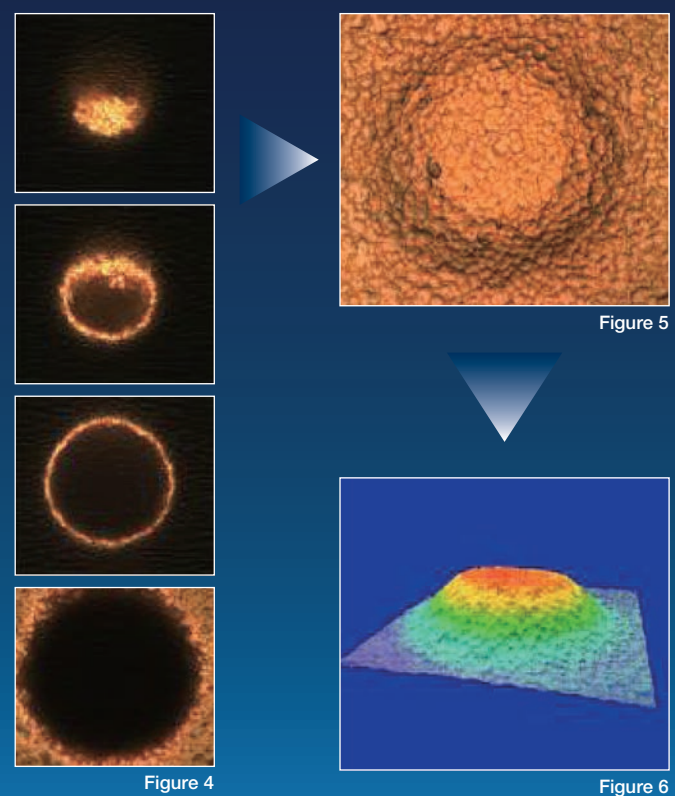
HYBRID continuously captures in-focus images of a sample being moved in z direction by taking advantage of the confocal optics principle that reflected light has its maximum brightness when it is in focus (Figure 4).

Effect1

By recording maximum brightness at each pixel, all-focused images can be captured (Figure 5).

Effect2

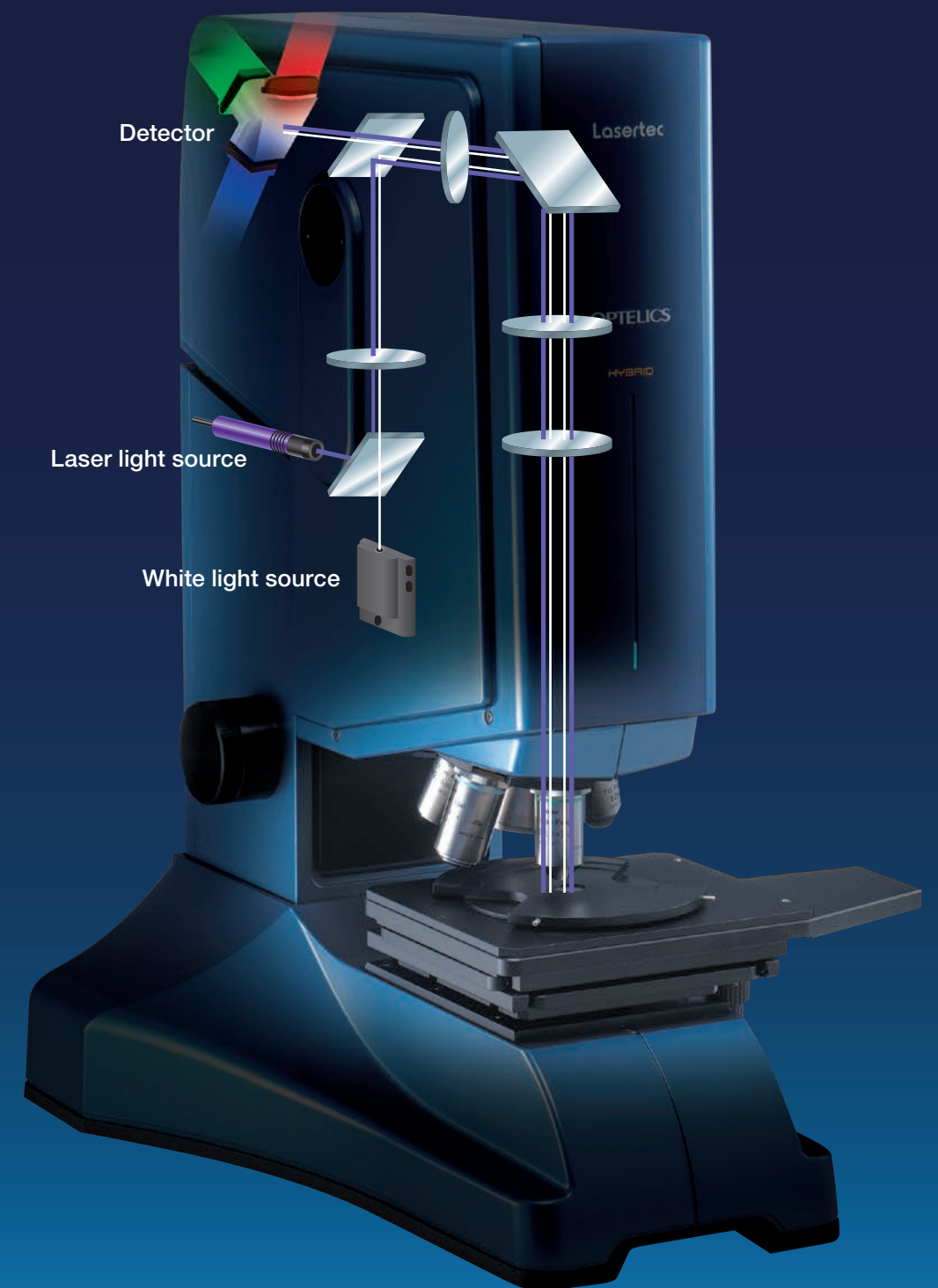
By recording the z position of each pixel at its peak brightness, 3D measurement such as shape and surface roughness measurement is possible (Figure6).

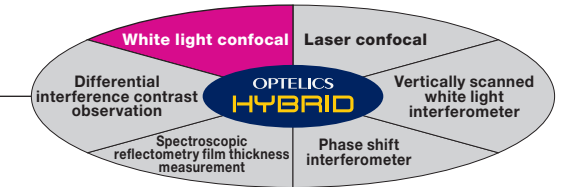


Unique confocal optics of HYBRID

Unique confocal optics of HYBRID

1. Two types of light source - white light and violet laser → Multiple functions and high-definition 24bit full color imaging
2. Detectors that detect each of RGB wavelengths simultaneously and separately → Detection channel switching function
3. Proprietary light scanning method that maximizes the performance of large-aperture low magnification objective lens → Up to 15mm wide FOV



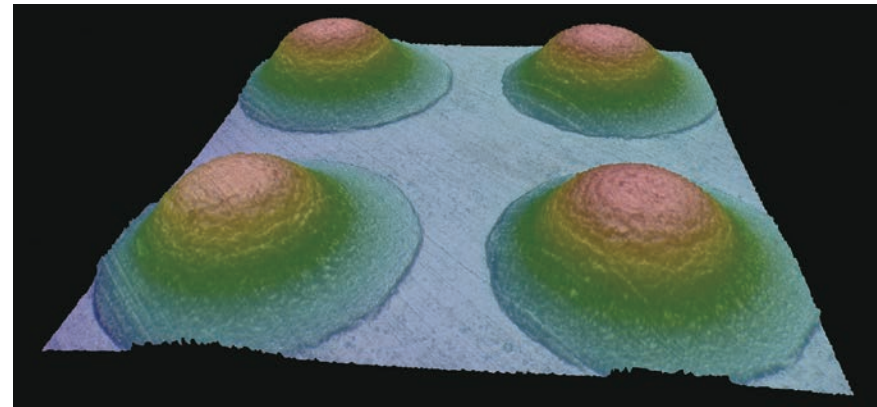
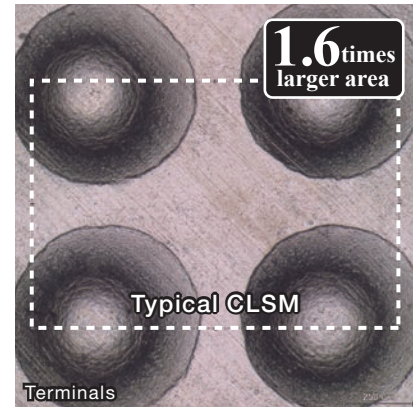


Wide FOV for efficient observation

FOV 1.6 times wider than a typical CLSM ※ When objective lens of the same magnification is used

10x objective lens (FOV 1,500μm)

3D image



High precision measurement at low magnification

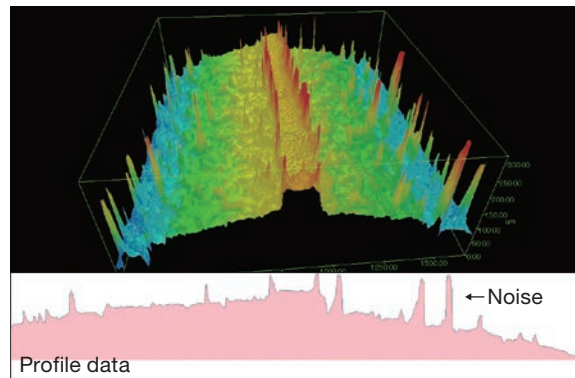
With the use of our special objective lens, high precision measurement at low magnification, which CLSM is hard to achieve, is made possible.

Objective lens designed especially for wide FOV and high precision measurement

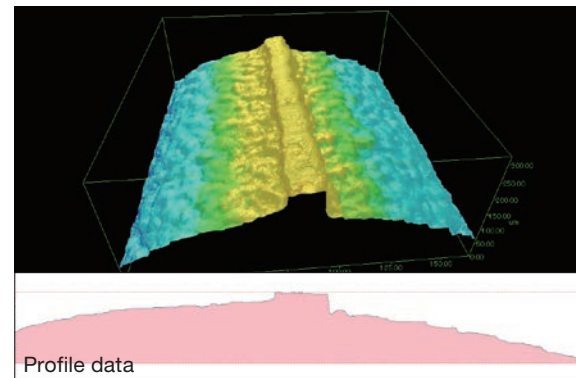
High-NA objective lens available for 5x, 10x, 20x magnification

Magnification	Normal objective lens NA	Special objective lens NA	FOV
5x	0.15	0.25	3,000×3,000μm
10x	0.30	0.50	1,500×1,500μm
20x	0.45	0.75	750×750μm

3D image from normal objective lens (10x)



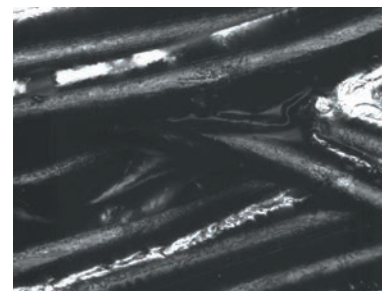
3D image from our special objective lens (10x)



Wide FOV and high precision

FOV 6.5 times wider than typical CLSM is possible, thanks to HYBRID's wide FOV and the use of special high-NA low magnification objective lens.

Image from typical CLSM
20x objective lens (NA 0.46)



Copper wire (FOV 670μm×500μm)

High-definition wide-FOV image available with HYBRID
10x objective lens (NA 0.50)

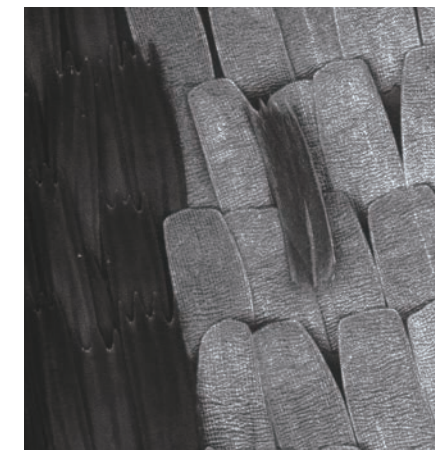


(FOV 1,500μm)

High-definition images of white light confocal

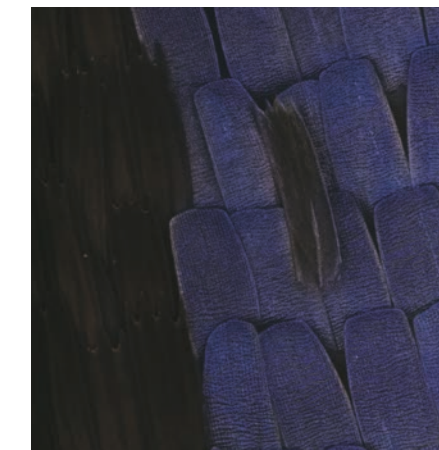
With the use of Xenon lamp similar to sunlight as light source, high-definition images with good color separation and high depth of field are available.

Black and white image from CLSM



Butterfly scales

Color image from CLSM



Composite image with non-confocal color image

Color image from HYBRID



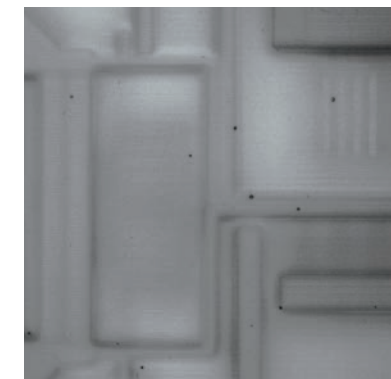
High definition image of white light confocal

Widening applications with detector channel switching

Detector channel switching allows observation and measurement to be performed in the most suitable wavelength. It also widens your applications to samples for which laser light cannot provide a clear picture.

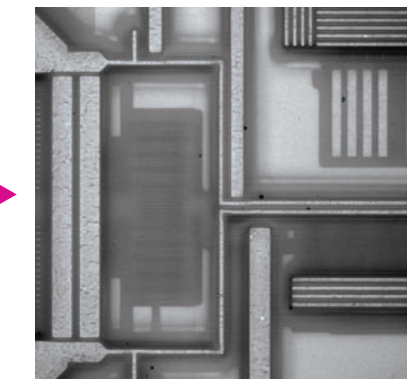
Different observation result of each channel

Upper layer observation: blue channel

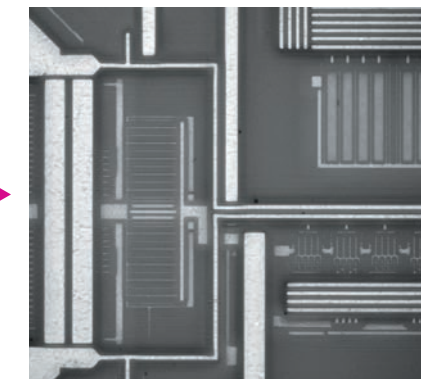


PI-coated communication device

Middle layer observation: green channel

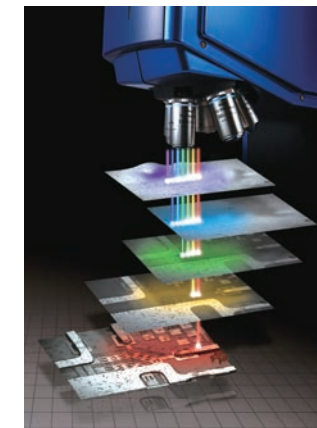


Lower layer observation: red channel

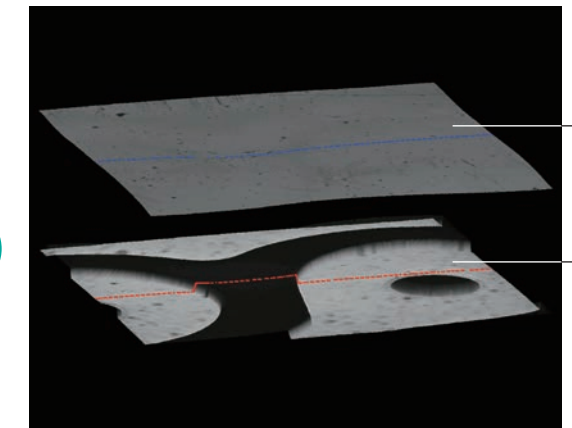


Widening applications with light wavelength selection

The selection of 6 different wavelengths of light source is available. It allows you to select the best wavelength for your observation and measurement and widens your applications to samples susceptible to damage in a particular wavelength of light, such as resist film or UV curable resin, and samples that absorb a particular wavelength of light.

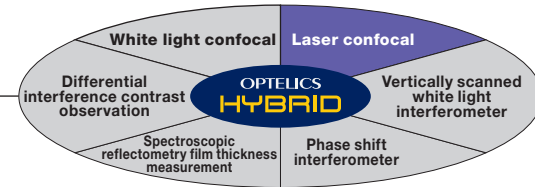


Multi layer observation using wavelength selection (concept illustration)



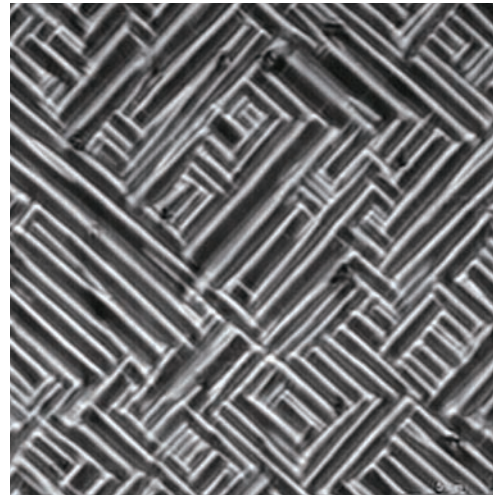
PI-coated flexible printed circuit board

PI coat surface (436nm)
Surface of substrate (633nm)

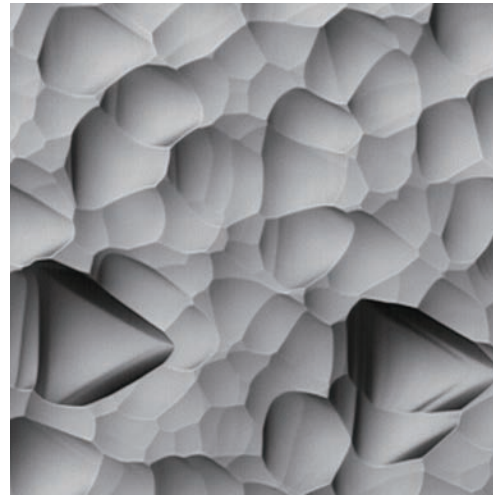


High-magnification, high-resolution observation

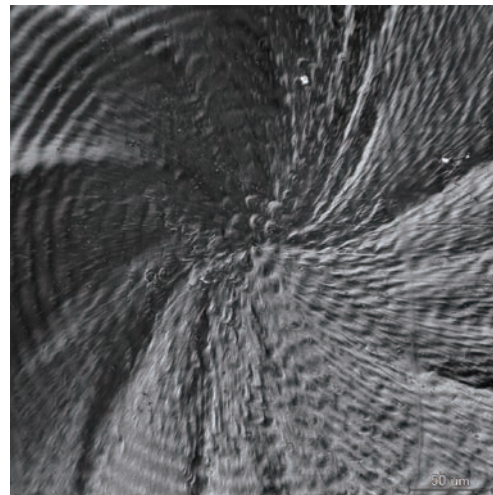
The 405nm-laser light source allows you to capture the nanometer-scale world in an instant. Ultrafine structures can be visualized clearly.



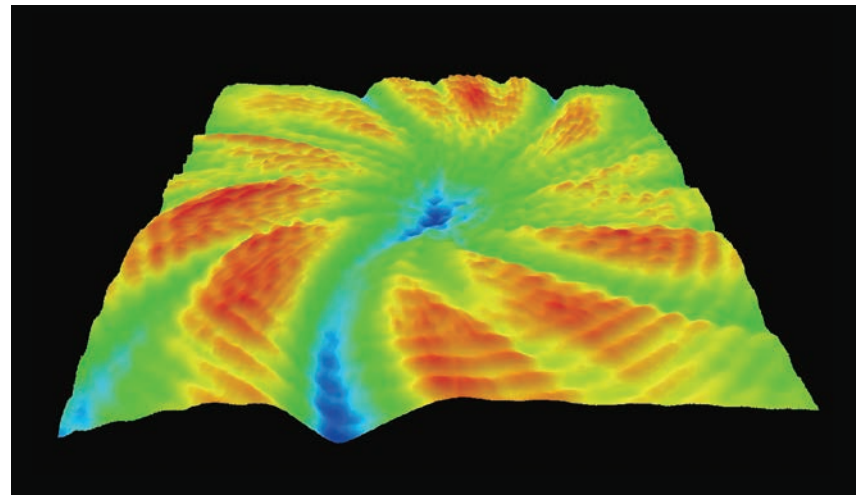
Sodium niobate domain observation
(FOV 25um, 11,000x magnification on monitor)



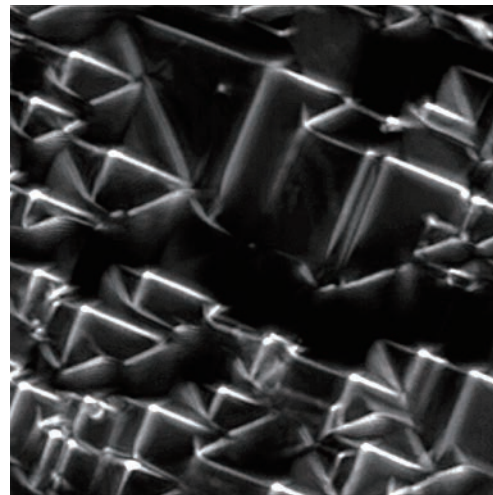
Si wafer backside
(FOV 75um, 3,700x magnification on monitor)



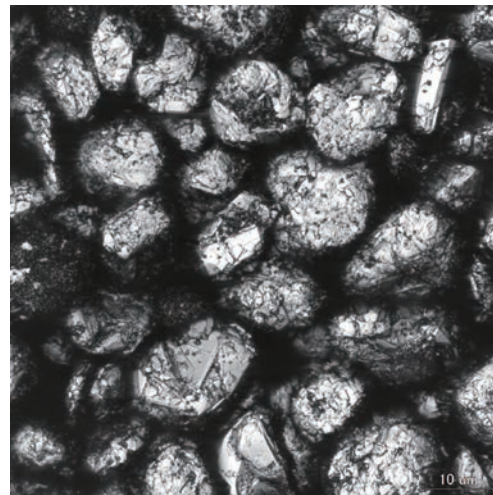
Polymer blend crystal
(FOV150um, 1,850x magnification on monitor)



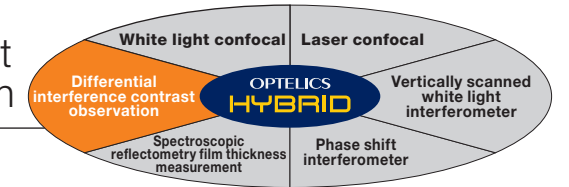
3D image of polymer blend crystal
(FOV150um)



Solar cell texture
(FOV50um, 5,500x magnification on monitor)



Active material of lithium ion battery
(FOV75um, 3,700x magnification on monitor)



Nanometer-scale surface morphology visualization

High contrast visualization of nanometer-scale surface morphology based on the combination of confocal and differential interference contrast (DIC) optics.

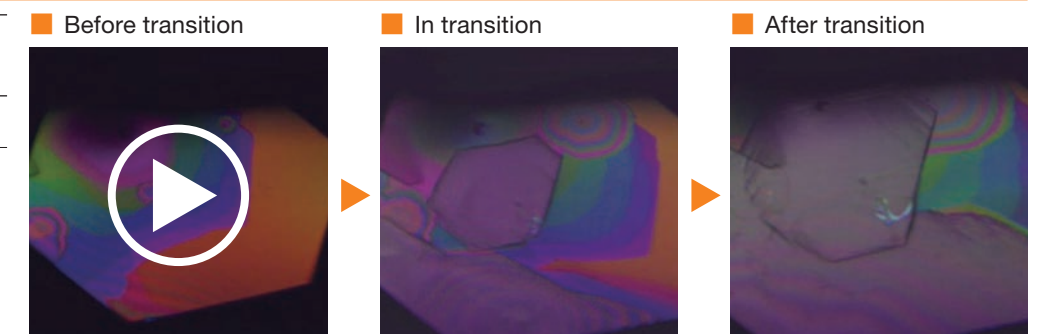
Without DIC	Digitally-processed DIC image	Optical DIC image from HYBRID
 Epitaxial defects on S:C (FOV 1,500um) not visible	 Not clear	 Clearly visible
 Step bunching on SiC wafer (FOV 1,500um) not visible	 Not clear	 Clearly visible
 GaN epitaxial defects (FOV 1,500um) not visible	 Not clear	 Clearly visible

In-situ observation

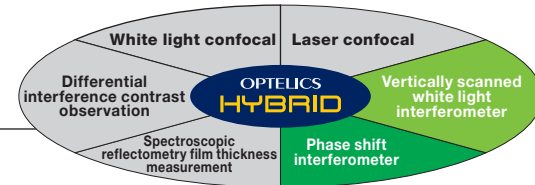
Real-time observation of liquid and other samples

Typical usages

- Observation of phase transition of metal and inorganic samples under changing temperature conditions
- Video capture of crystal growth or phase transition in liquids



Crystal growth and transition in a cadmium iodide liquid (high-definition video capture and playback at high speeds up to 15 frames per second is available)



Nanometer-scale height measurement in a wide FOV

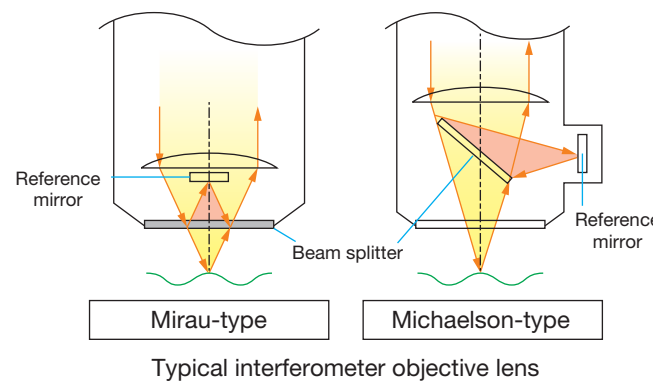
Nanometer-scale precise height measurement in a millimeter-scale FOV is possible.

Features

The resolution in height measurement using optical interference is independent from objective lens NA. It is therefore possible to have high resolution even in a wide FOV. This is suitable for measuring ultrafine concave/convex, surface roughness and unevenness while maintaining a millimeter-scale wide FOV. You can dramatically broaden a range of measurement applications by complementing this method with confocal, which is more suited to measure slopes and rough surfaces.

Basic principle of optical interference measurement

Surface profiles are measured in nanometer-scale resolution from the analysis of interference patterns generated by interference objective lens. Light is split into two arrays by a beam splitter inside the objective lens. One of the arrays is reflected by the sample surface while the other array goes to the reference mirror and reflected there. Both reflected beams are superimposed in the objective lens to form interference patterns caused by optical path differences. As the tool is adjusted to have no optical path difference in a focus position, interference fringes indicate concaves and convexes on sample surface.

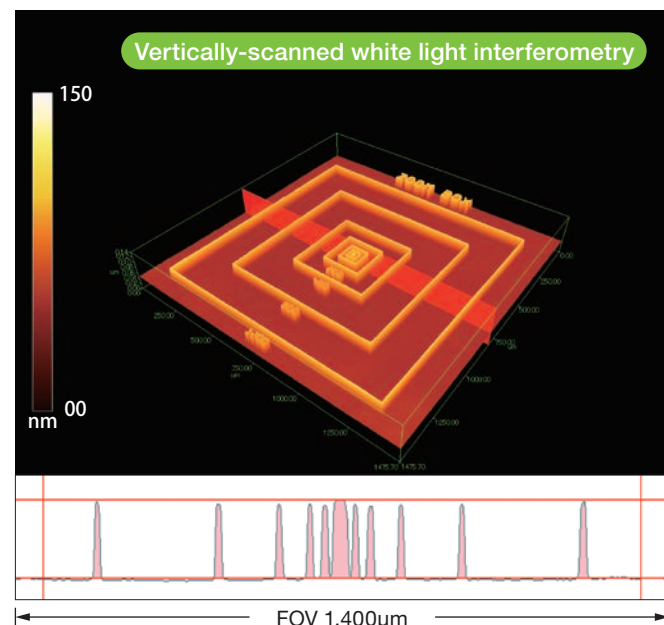


Two types of interference measurement method

Vertically-scanned white light interferometry

Interference fringes have the strongest contrast at in-focus plane. The peak of brightness in interference fringe is detected to measure height with the operability of confocal microscope.

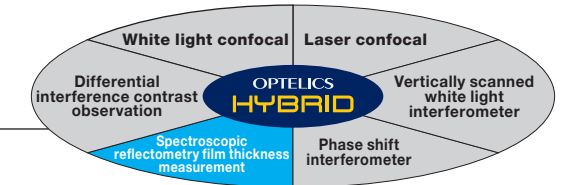
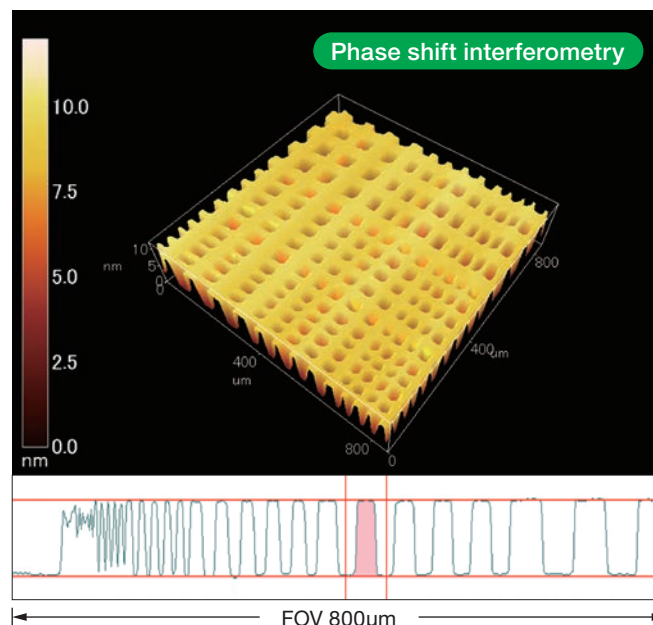
Example of measurement (45nm height)



Phase shift interferometry

Height measurement in Angstrom-scale accuracy is available from the phase analysis of interference fringes in a single wavelength of light (546nm) that are obtained as the phase is being changed in multiple steps. The measurement range is limited within a half wavelength but the merit is its short measurement time, which is a few seconds.

Example of measurement (8nm in height)



Transparent film thickness measurement

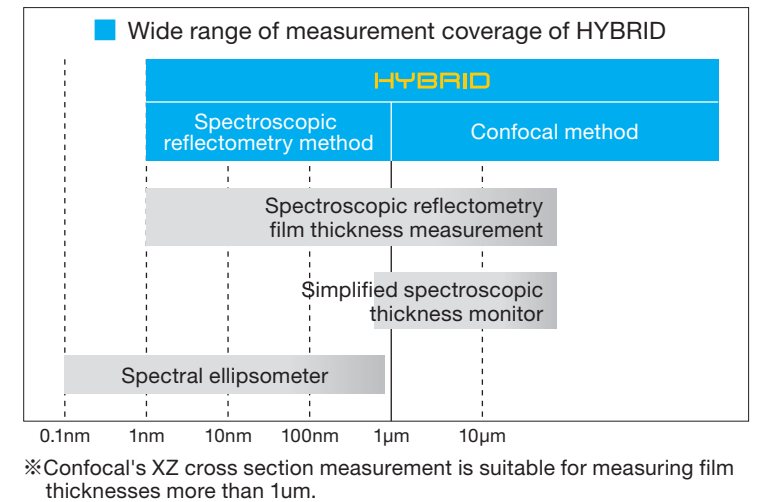
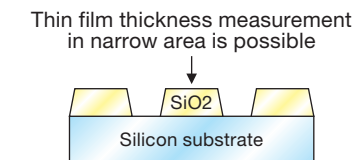
You can measure the thickness of transparent films using the capability to select 6 wavelengths in white light. Measurement area is user-settable. This function is applicable to either all surface coated films or patterned films.

Features

Spectroscopic reflectometry is available to measure transparent film thickness in nanometer scale. It compensates for the shortcoming of confocal optics, which cannot detect a focus position for a film with thickness close to the wavelength of light, thus failing to measure the thickness. HYBRID offers this spectroscopic reflectometry to broaden its applications to such a thin film measurement.

Samples

- Oxidized film
- SOI multi-layer film
- Other transparent film
- Residue from etching



Principle of spectroscopic reflectometry

Spectroscopic reflectometry

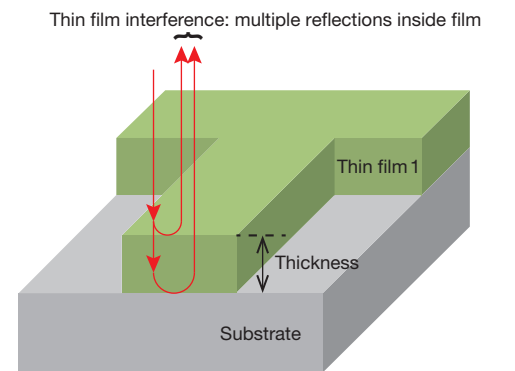
Film thickness can be measured using the reflectance spectrum obtained from spectroscopic reflectometry after parameter fitting with optical simulation model.

Reflectance spectrum

It shows the relation between absolute reflectance and wavelength. It varies depending on film thicknesses and optical constants.

Absolute reflectance

It is determined by thin film interference caused by multiple reflections of light between film surface and substrate.

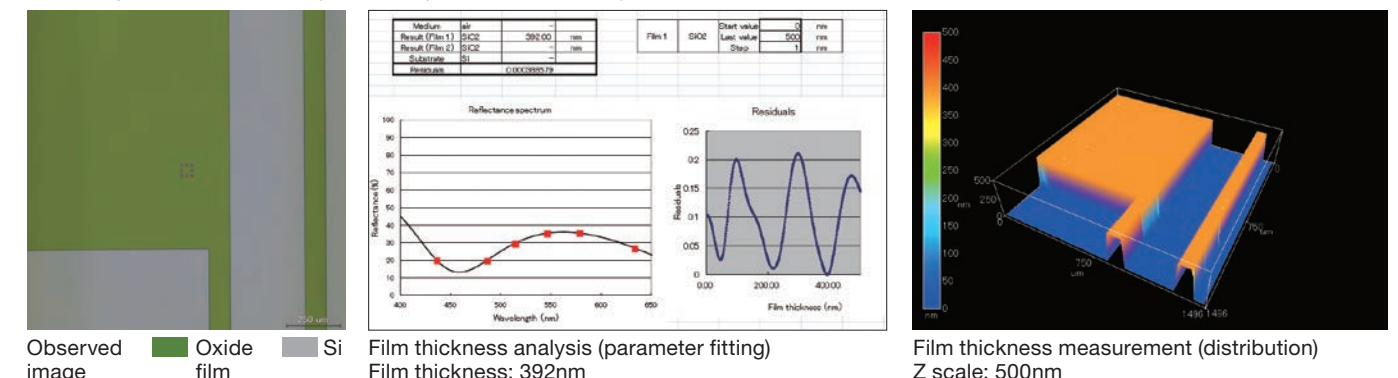


Spectroscopic reflectometry of HYBRID

Six wavelengths are selected from white light to obtain a reflection image for each and to calculate reflectance.

Optical constants (refractive index and extinction coefficient) for thin film and substrate are used in optical model to calculate absolute reflectance from Fresnel coefficient and to measure film thickness after parameter fitting.

Example of measurement (Oxide film patterns on Si wafer)



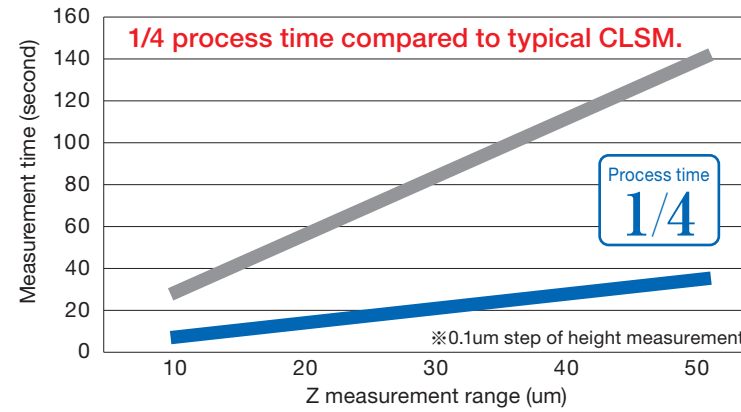
High speed and high precision measurement

White light confocal and laser confocal

Industry-leading measurement speed

Industry-leading speed

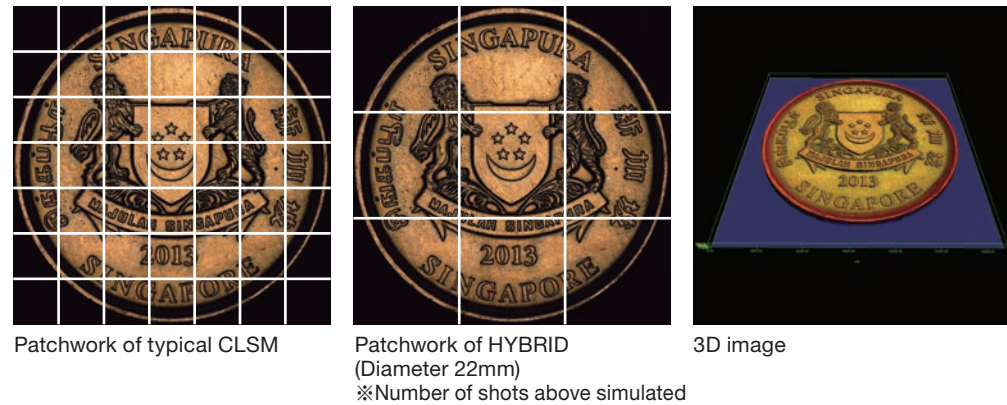
HYBRID achieves 15Hz frame rate, about 4 times faster than a typical CLSM, which makes it a powerful tool for high-speed auto measurement, patchwork and high-speed video observation.



High speed patchwork

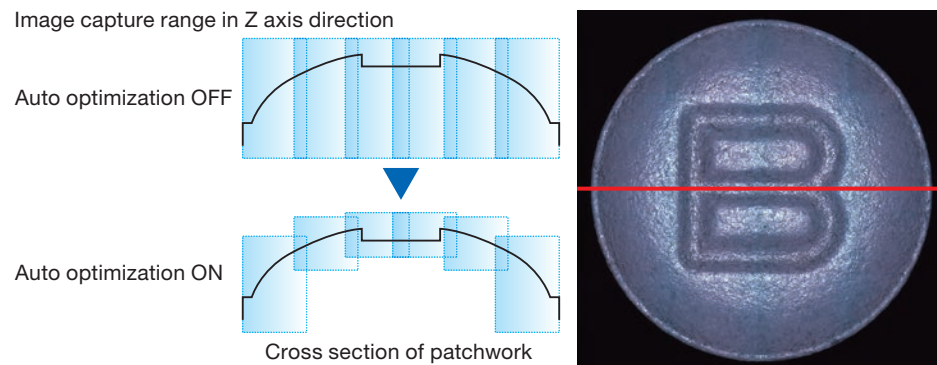
This function allows you to stitch a large object as the one shown on the right with ease. It creates a wide FOV image smoothly. The process time is about 1/6 of that required for a typical CLSM. (Number of screens required: 1/1.5, measurement time per screen: 1/4)

Process time 1/6



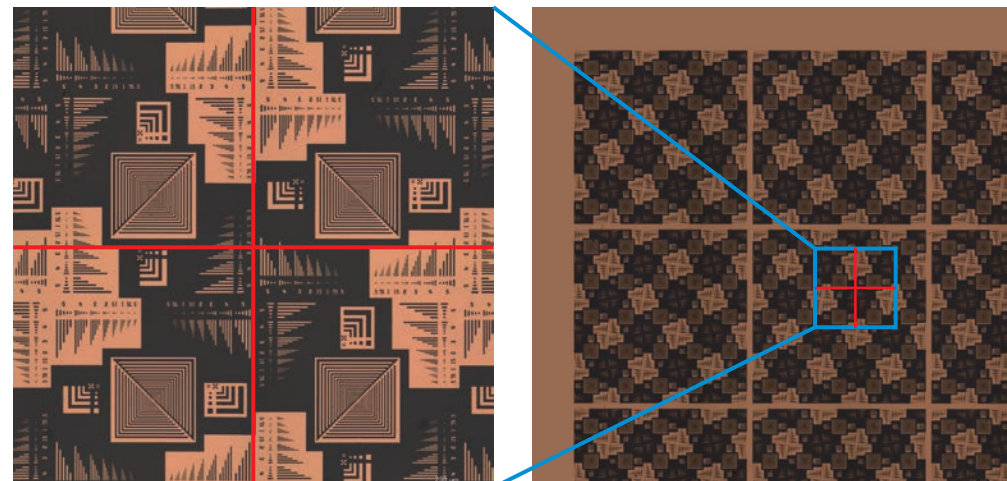
High-speed automatic optimization of measurement range

In patchwork, height gap within each FOV is automatically detected to adjust measurement range. It prevents image input errors and dramatically shortens scan time.



Area mapping

Current measurement position can be displayed on a wider FOV image. The function also allows you to move to the measurement point with one click, auto patchwork in a specified area on the map and coordinate information control in a specified position.



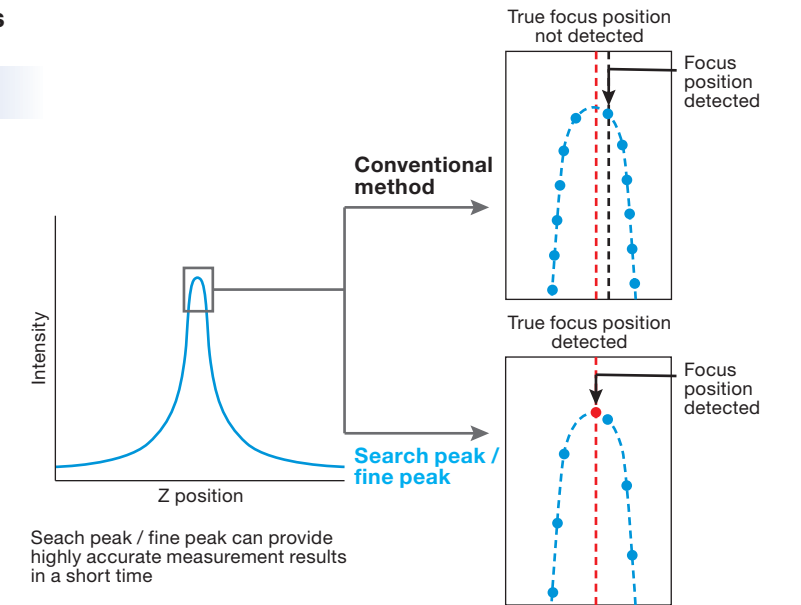
Industry-leading measurement accuracy and repeatability

Industry-leading measurement accuracy

High accuracy required for measurement tools

High accuracy

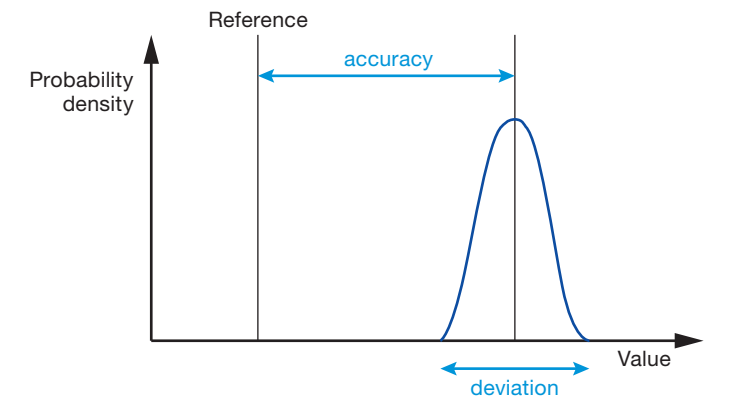
Line width: $\pm[0.02 \times (100 / \text{objective}) + L / 1000] \mu\text{m}$
 Height measurement: $\pm(0.11 + L / 100) \mu\text{m}$
 Both at industry-leading level



Search peak / fine peak can provide highly accurate measurement results in a short time

High level of repeatability

Line width measurement $3\sigma : 10\text{nm}$
 Height measurement $\sigma : 10\text{nm}$
 HYBRID achieves an industry-leading repeatability and detects a true peak located in a measurement gap based on IZ curve calculated with a special algorithm.

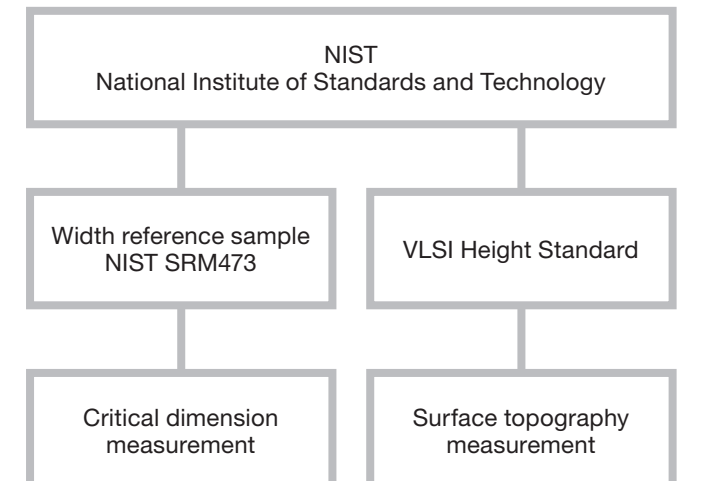


Reliability

Outgoing inspection is performed on HYBRID using reference samples with correct traceability to ensure strict quality assurance.

Traceability system

OPTELICS HYBRID is calibrated conforming to the standards traceable to National Institute of Standards and Technology



Various measurement and analytical functions

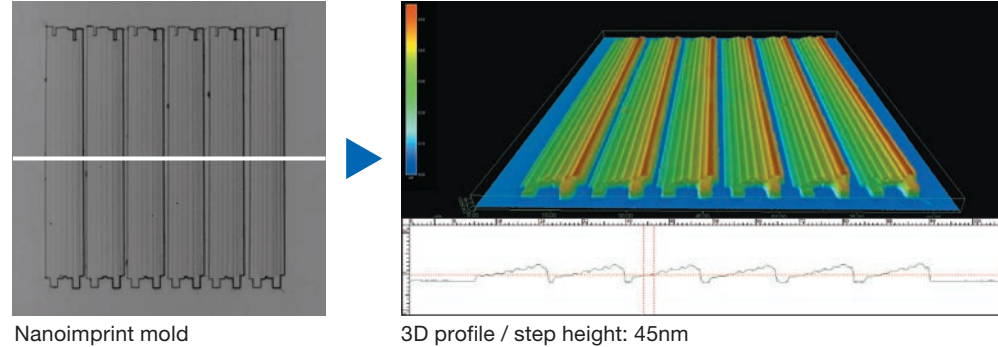
White light confocal and laser confocal

Applicable to various usages

Profile / comparison measurement

Surface shape measurement on a user-specified line. Comparison measurement is available for measuring the difference in multiple lines.

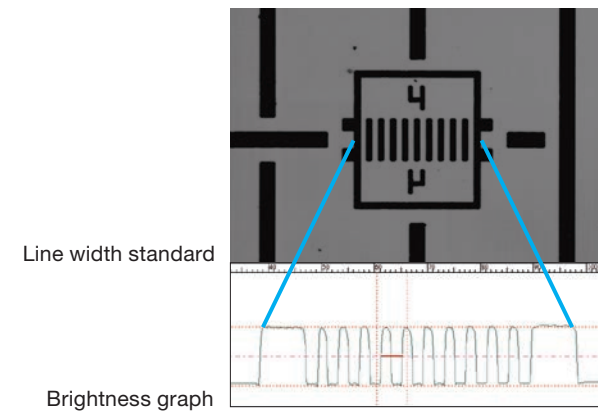
- Measurement criteria: width, height, angle, proximate radius, deviation



Width and pitch measurement

Ideal for measuring semiconductor pattern line widths. Industry-leading accuracy and repeatability is achieved with unique optics and detectors.

- Accuracy: $\pm[0.02 \times (100 / \text{objective magnification}) + L / 1000] \mu\text{m}$ (Ex. $\pm 0.025 \mu\text{m}$ for $5 \mu\text{m}$ line width)
- Repeatability: $3\sigma = 0.01 \mu\text{m}$



Surface roughness measurement

Surface roughness measurement conforming to JIS and ISO parameters. High resolution roughness measurement is possible for any type of samples thanks to its non-contact measurement.

2 dimensional roughness

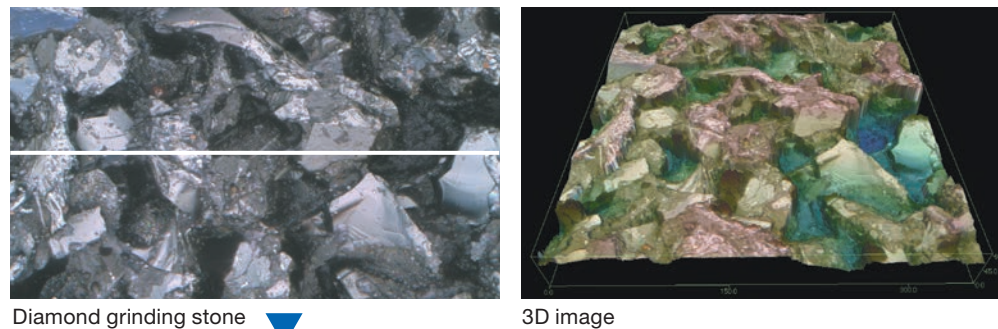
Surface roughness: Ra, Rp, Rv, Rc, Rt, Rq, Rsm, Rk, Rpk, Rvk, etc. JIS B0671: Rk, Rpk, Rvk, Mr1, Mr2, A1, A2, etc.

Rmr

3D roughness

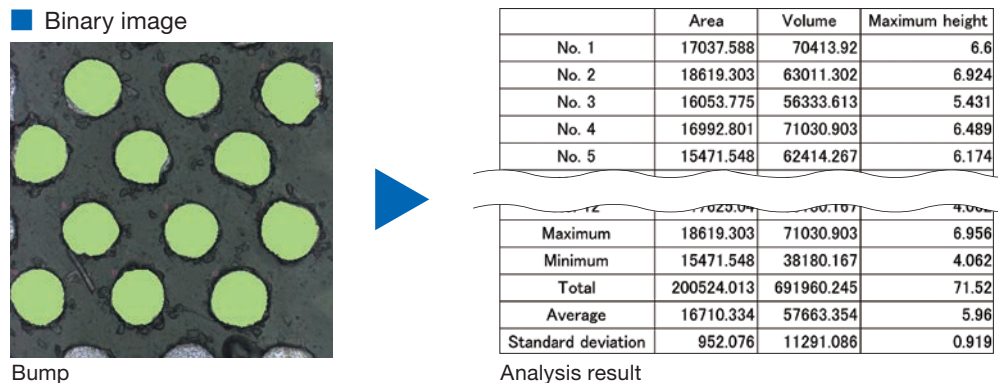
Roughness parameters: Sa, Sp, Sv, Sz, Sq, etc.

Volume parameters: Sk, Spk, Svk, Smr1, Vvc, Vvv, etc.



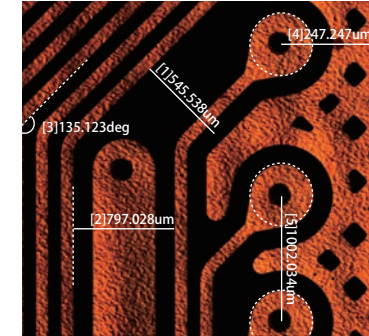
Analysis of geometric properties

HYBRID analyzes more than 20 properties including area, volume, center of gravity, etc. Output of analysis result is available in a spreadsheet format.



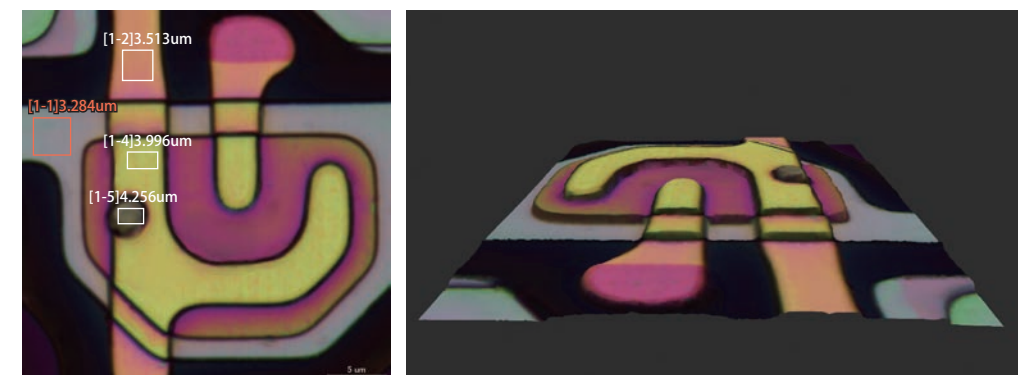
2D measurement

Measurement of 2 dimensional features such as length, angles, radius and counting of features



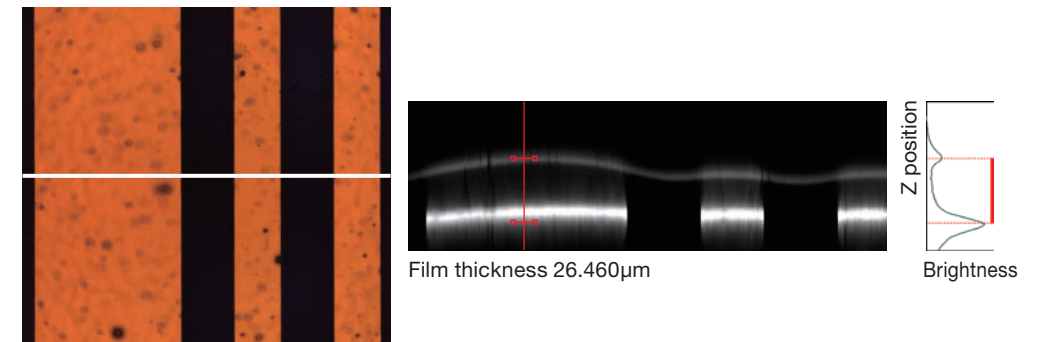
Height difference measurement

Measurement of height difference in a user-specified area



Film thickness measurement (XZ cross section measurement)

Film thickness is obtained by optically calculating the distance between film surface and substrate surface using reflected light.



Data management

LMWS file

A dedicated file for storing measurement conditions, results, etc.

Spreadsheet

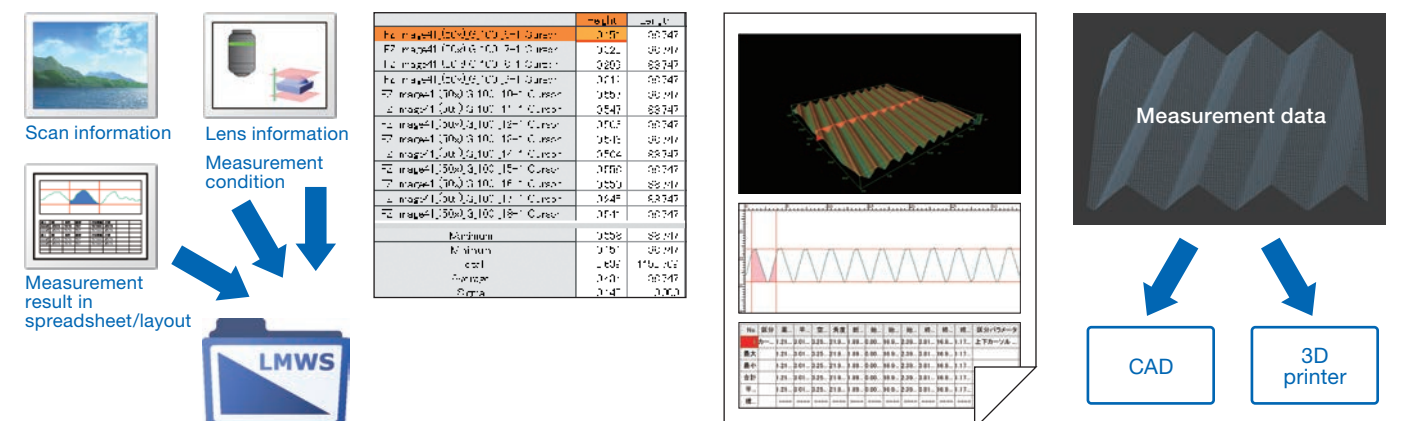
A spreadsheet for storing multiple measurement data

Layout report

Capability to generate reports containing images and measurement data charts

Data output

Output in image file, CSV file and CAD data (STEP file) is available



Ease of use and high skills for all users

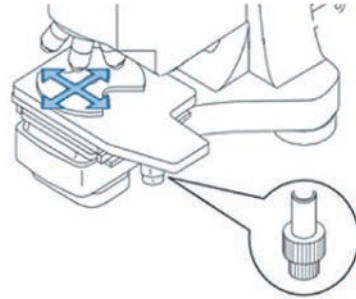
Expert mode and Beginner's mode



Example of operation guidance in Beginner's mode

1. Adjusting XY of the observation position

Move the observation position to the center of the screen. Use the UP, DOWN, LEFT and RIGHT buttons of the XY control or click on the screen to move the stage.



Expert mode

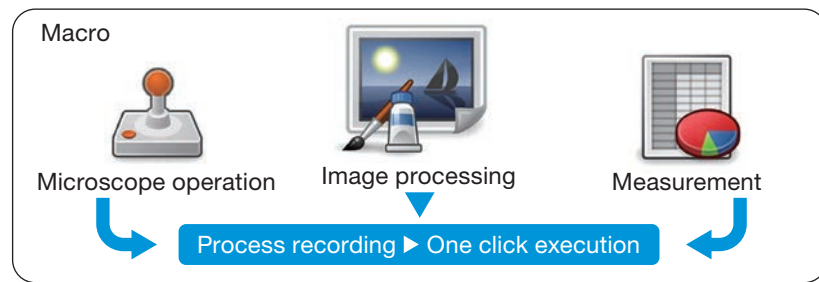
Use this mode for advanced operation and detailed setting.

Beginner's mode

"Operation Guidance" gives you step-by-step instructions to walk you through the measurement process.



Macro



One click on Play button does it all!



Expert

Operate a measurement sequence or analysis process while saving commands in a macro.

No.	Category	Description	Data
1	Control	Light path setting	Commar
2	Control	Auto focus	Commar
3	Control	Auto scan setting	Commar
4	Control	Z scan	Commar
5	Filter	Median	Commar
6	Geometrical conversion	Horizontal correction	BaseOff
7	Measurement	Profile measurement	AddExist
8	Measurement	Roughness measurement	AddExist
9	File	Save (image)	Commar



Operator

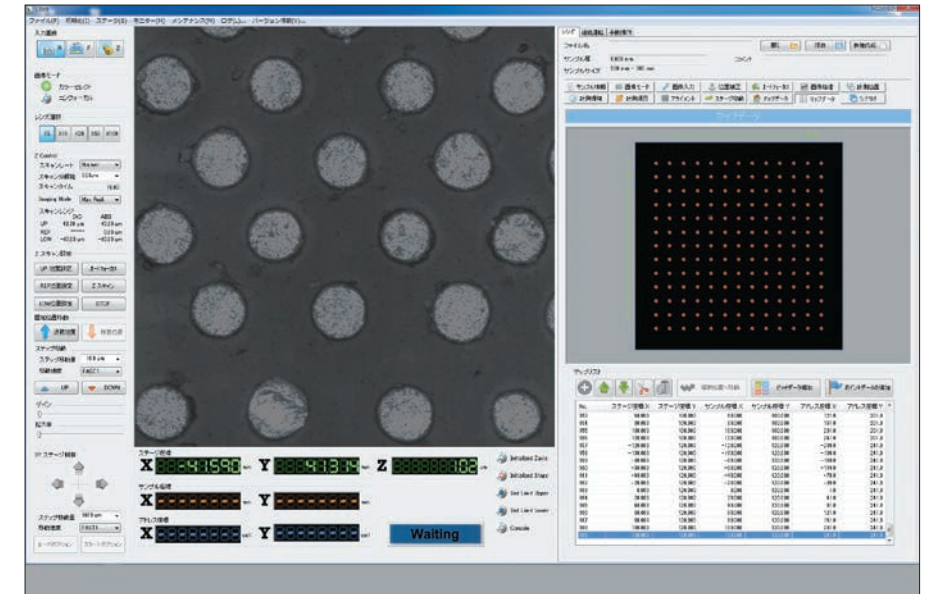
Perform the expert's measurement and analysis with one click that recalls the saved commands.

Options

Software programs for automated operation

Auto-measurement software

This software is used with a motorized stage to automatically perform pre-set recipes, for example, on the measurement of semiconductor pattern dimensions and surface roughness.

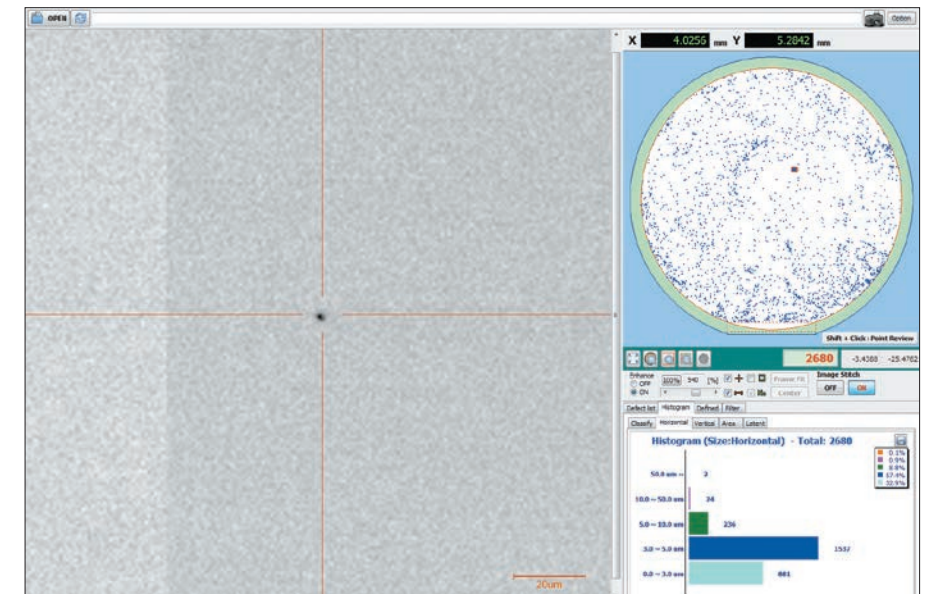


Auto-measurement of bumps

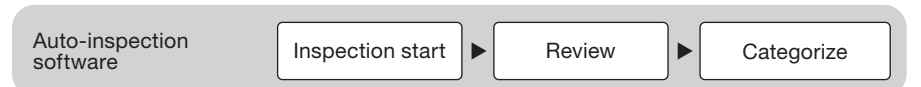


Auto-inspection software

This software is used to inspect a whole wafer or glass substrate for small defects and particles on surface. It also enables you to review defects in an area specified on defect-distribution map and categorize each defect (e.g., by size, white/black, pit/bump).



Whole wafer inspection for 0.5µmPSL



Options

Optional features for your specific needs

Motorized stage

The motorized stage significantly enhances the efficiency of sequential and patchwork measurements. (XY stroke 150mm x 150mm)



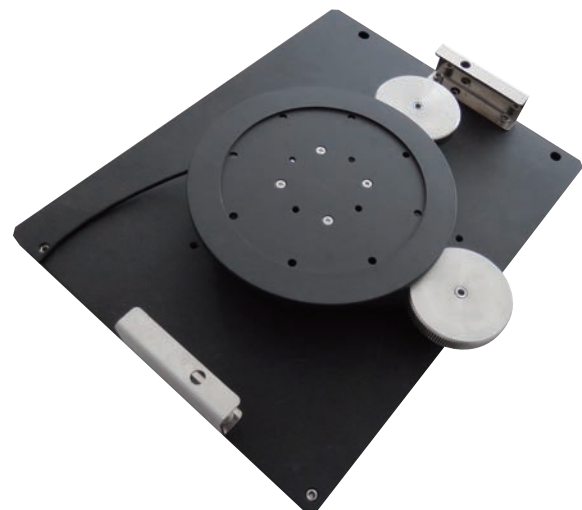
Electrostatic holder

This is a stage to hold a film sample with static electricity.



Tilt stage

This is a stage to hold a sample in a tilted position for interference measurement and roughness measurement.



Large / special stage

We can provide specially-designed stages to meet your various needs based on our inspection expertise.



Flexibility

Specifications

Model / Specification		Basic functions	Multifunctions	Diverse applications	
		Basic model C3	Standard model L3	High-end model L7	
		White light confocal	White light confocal Laser confocal	White light confocal Laser confocal Differential interference Optical interference measurement Spectroscopic reflectometry film thickness measurement	
Light source	Laser	-	405nm	405nm	
	Xenon / Hg-Xe	R,G,B	R,G,B	436nm,486nm,514nm,546nm, 578nm,633nm,White light	
FOV / Magnification	White light	Objective lens	FOV (HxV)		
		On-screen magnification			
		1x	18.5x	15,000x15,000 μm	
		2.5x	46.2x	6,000x6,000 μm	
		5x	92.5x	3,000x3,000 μm	
		10x	185x	1,500x1,500 μm	
		20x	370x	750x750 μm	
	Laser	50x	1,850x	-	150x150 μm
		100x	3,700x	-	75x75 μm
		150x	5,550x	-	50x50 μm
Zooming		1~8x			
Frame memory	Brightness	1,024x1,024x12bit / High definition mode 2,048x2,048x12bit			
	Height	1,024x1,024x16bit / High definition mode 2,048x2,048x16bit			
Frame rate		15Hz~120Hz			
Width measurement	Minimum unit of measurement	0.001 μm			
	Accuracy	± [0.02x(100/Objective lens magnification) + L/1000] μm			
	Repeatability (3σ) ^{※1}	10nm			
Height measurement	Scale resolution	0.1nm			
	Accuracy	± (0.11+L/100) μm			
	Repeatability (σ) ^{※2}	10nm			
	Measurement range ^{※3}	7mm			
Z stroke		100mm	80mm		
Nosepiece		5-hole motorized revolving nosepiece (with auto lens position recognition)			
XY stage	Manual	○	-		
	Motorized	Options	○		
Differential interference contrast observation		Options	○		
Optical interference measurement		Options	○		
Spectroscopic reflectometer measurement		Options	○		
Software	Image capture	Patchwork, HDR mode, search peak, first peak, multi-gain, etc.			
	Basic functions	Measurement of height, line width and surface roughness (JIS, ISO), and 3D display			
	Image processing	Filter, tilt correction, binarization, nose elimination, bit depth conversion, size conversion, color balance, etc.			
	Geometric property calculation	About 20 properties including area, volume, surface area, Feret diameter, center, roundness, maximum length, aspect ratio, etc.			
Report generation		Layout, image database, template, file extension batch conversion			
Utility		AC 100-240V, 50/60Hz, 1,500VA			
Dimensions and weight	Microscope unit	382(W) x 511(D) x 669(H) mm 41kg			
	Control unit	431(W) x 450(D) x 106(H) mm 7.1kg			
	Light source unit	142(W) x 311(D) x 227(H) mm 6.7kg			
	PC	175(W) x 417(D) x 360(H) mm 9.6kg			
Traceability		○			

※1 Based on reference pattern measurement using 150x (NA0.95) under no vibration condition.
 ※2 Based on the measurement of VLSI Standards' step height standards using 100x (NA0.95) under no vibration condition.
 ※3 Up to the maximum distance of objective lens movement